

Title (en)

Conductor lead through, housing apparatus and method for manufacturing a conductor lead through

Title (de)

Leiterdurchführung, Gehäusevorrichtung, Feldgerät und Verfahren zur Herstellung einer Leiterdurchführung

Title (fr)

Traversée de conducteur, boîtier d'appareillage et méthode de fabrication d'une traversée de conducteur

Publication

EP 2093846 B1 20110817 (DE)

Application

EP 08101804 A 20080220

Priority

EP 08101804 A 20080220

Abstract (en)

[origin: EP2093846A1] The leadthrough (100) has a sealing device with a grouting device (117) and a separating unit (114) e.g. disk. The grouting device is arranged in a section of a hollow inner region (124) of an outer conductor (101) e.g. housing coupler, such that the grouting device lies at the unit. The sealing device is arranged along the hollow region so that the sealing device provides a leakage rate whose value is below a predetermined value of a leakage rate, where an electrical signal with a predetermined frequency is transmitted along a longitudinal axis by of the conductor from the leadthrough. Independent claims are also included for the following: (1) a housing device comprising a housing separating device (2) a method for manufacturing a conductor leadthrough.

IPC 8 full level

H01R 13/646 (2011.01); **H01R 13/52** (2006.01)

CPC (source: EP US)

H01R 13/5216 (2013.01 - EP US); **H01R 24/44** (2013.01 - EP US); **H01R 13/533** (2013.01 - EP US); **H01R 24/50** (2013.01 - EP US); **H01R 2103/00** (2013.01 - EP US); **Y10T 29/4922** (2015.01 - EP US)

Cited by

DE102019102812A1; EP2487472A3; CN103368125A; CN111521238A; DE102009051072A1; EP2683022A1; DE202019100659U1; WO2014006148A1; WO2014006150A1; US9212942B2; EP2683023A1; US8632666B2; EP2930476A1; EP3076139A1; US10205245B2; EP3693712A1

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